

**PLEASE AMEND THE SPECIFICATION AS FOLLOWS:**

After the title, insert -- This is a division of Patent Application serial number 10/154,662, filing date 5/24/02, which is a Continuation-In-Part application of serial number 10/058,259, filing date 1/29/02, which is a Continuation application of serial number 09/251,183, filing date 2/17/99, now issued as US Patent 6,383,916, which is a Continuation-In-Part application of serial number 09/216,791, filing date 12/21/98, Top Layers Of Metal For High Performance IC's, all of which are herein incorporated by reference in their entirety.

**REMARKS**

A reference to the parent case has been added by Preliminary Amendment to this Divisional Patent Application.

The application is believed to be in condition for allowance. Allowance of the subject Patent Application is therefore respectfully requested.

Respectfully submitted,

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